

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): A resin molded component, comprising a metal coating ~~treatment~~ provided on the surface thereof by a physical deposition method ~~chosen~~ selected from at least one method consisting of sputtering, vacuum deposition, and ion plating, after the surface is activated by a plasma treatment,

wherein the resin molded component comprises a resin composition comprising a base resin ~~containing a thermoplastic resin or a thermosetting resin~~ comprising at least one member selected from the group consisting of polyphthalamide and polyphenylene sulfide, and an elastic material, wherein the elastic material comprises at least one copolymer selected from the group consisting of ethylene -glycidyl methacrylate-methyl acrylate copolymer, ethylene-maleic anhydride-ethyl acrylate copolymer, graft copolymer of ethylene -glycidyl methacrylate copolymer and acrylonitrile-styrene copolymer, and ethylene -glycidyl methacrylate-ethylene ethyl acrylate copolymer.

Claim 2 (Canceled).

Claim 3 (Previously Presented): The resin molded component according to Claim 1, wherein the elastic material is present in an amount of from 0.5 to 10 parts in mass to 100 parts in mass of said base resin.

Claim 4 (Canceled).

Claim 5 (Previously Presented): The resin molded component according to Claim 1, wherein said resin composition further comprises an inorganic filler.

Claim 6 (Previously Presented): The resin molded component according to Claim 5, wherein said inorganic filler is fibrous having a diameter of from 0.5 to 5 μm and a length of from 10 to 50 μm .

Claim 7 (Previously Presented): The resin molded component according to Claim 5, wherein said inorganic filler is plate-form.

Claim 8 (Previously Presented): The resin molded component according to Claim 5, wherein said inorganic filler is a combination of a fiber form having a diameter of from 0.5 to 5 μm and a length of from 10 to 50 μm with a plate-form inorganic filler.

Claim 9 (Previously Presented): The resin molded component according to Claim 5, wherein said inorganic filler is spherical.

Claim 10 (Previously Presented): The resin molded component according to Claim 5, wherein said inorganic filler is present in an amount of from 40 to 75% in mass with respect to said whole resin composition.

Claim 11 (Previously Presented): A printed circuit board, comprising the resin molded component according to Claim 1.

Claim 12 (Previously Presented): The resin molded component according to Claim 1, wherein said resin composition further comprises a plate-form inorganic filler comprising at least one member selected from the group consisting of talc, mica, glass flake, monmorillonite, and smectite.

Claim 13 (Previously Presented): The resin molded component according to Claim 1, wherein said elastic material comprises ethylene -glycidyl methacrylate-methyl acrylate copolymer.

Claim 14 (Previously Presented): The resin molded component according to Claim 1, wherein said elastic material comprises ethylene-maleic anhydride-ethyl acrylate copolymer.

Claim 15 (Previously Presented): The resin molded component according to Claim 1, wherein said elastic material comprises graft copolymer of ethylene -glycidyl methacrylate copolymer and acrylonitrile-styrene copolymer.

Claim 16 (Previously Presented): The resin molded component according to Claim 1, wherein said elastic material comprises ethylene -glycidyl methacrylate-ethylene ethyl acrylate copolymer.

DISCUSSION OF THE AMENDMENT

Claim 1 has been amended by incorporating the subject matter of Claim 4 therein; Claim 4 has been cancelled. In addition, Claim 1 has been amended by deleting the superfluous word "treatment" and by replacing "chosen" with the synonymous --selected --.

No new matter has been added by the above amendment. With entry thereof, Claims 1, 3 and 5-16 will be pending in the application.